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No. 1043 P. 1

Attorney Docket No.: CPAC 1017-5
Application No. 10/632,552

SEP 05 2006

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS

Application No.: 10/632,552

Filed: August 2, 2003

Title: Semiconductor multi-package module having
package stacked over die-up flip chip
ball grid array package and having wire
bond interconnect between stacked packages

)
) Examiner: Chris C. CHU
)
) Group Art Unit: 2815
)
) Date: September 5, 2006.

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to
Examiner, Chris C. Chu in the United States Patent and Trademark Office, at
the Central Fax no. 571 273-8300 on September 5, 2006.

Signed


Bill Kennedy

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COMMISSIONER FOR PATENTS
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ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed July 5, 2006, kindly amend the application as follows.

Amendments to the Claims are reflected in the Listing of Claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.